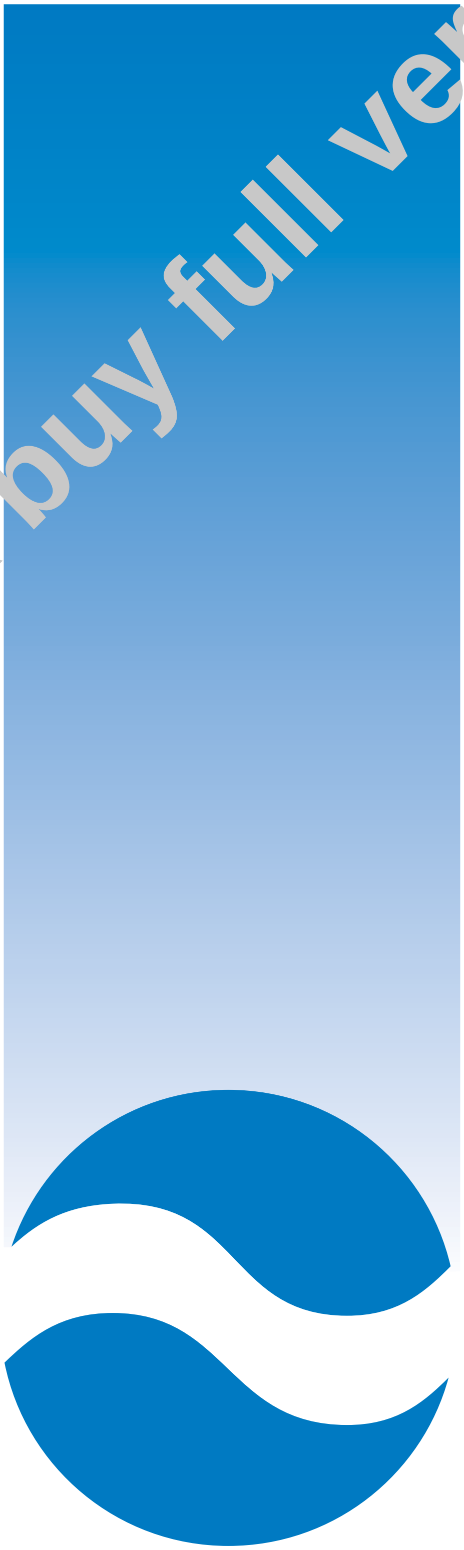
IPC J-STD-004B
w/Amendment 1
November 2011
Supersedes J-STD-004B
December 2008

JOINT INDUSTRY STANDARD

Requirements for Soldering Fluxes



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- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Increase time-to-market
- Keep people out
- Increase cycle time
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IPC J-STD-004B with Amendment 1

Requirements for Soldering Fluxes

A standard developed by the Flux Specifications Task Group (5-24a) of the Assembly and Joining Processes Committee (5-20) of IPC

Supersedes:
J-STD-004B - December 2008
J-STD-004A - January 2004
J-STD-004 - January 1995
Amendment 1 - April 1996

Users of this publication are encouraged to participate in the development of future revisions.

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Acknowledgment

Any document involving a complex technology draws material from a vast number of sources. While the principal members of the Flux Specifications Task Group (5-24a) of the Assembly and Joining Processes Committee (5-20) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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